eFuse IC Glossary

Outline:

This document explains the glossary in the datasheet (absolute max. rating, operating range, and electrical characteristics) of eFuse IC (electronic fuse) that solves the disadvantages of conventional fuses (tube-type fuses and polyswitches).

This IC uses a current/voltage detector and a MOSFET to shut off the power supply in a short time of about 150ns with high current accuracy.

In addition to saving labor for fuse replacement, various protection functions (overcurrent protection, overvoltage protection, short-circuit protection, etc.) are incorporated to improve the safety of the system.

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1. Absolute Maximum Ratings

Term	Symbol	Description
Input voltage	$V_{\rm IN}$	The maximum rated voltage that can be applied to the VIN pin without causing permanent damage to an IC or degrading its characteristics or reliability
ILIM voltage	V _{ILIM}	The maximum rated voltage that can be applied to the ILIM pin without causing permanent damage to an IC or degrading its characteristics or reliability
dV/dT voltage	V _{dV/dT}	The maximum rated voltage that can be applied to the dV/dT pin without causing permanent damage to an IC or degrading its characteristics or reliability
Control voltage	V _{EN/UVLO}	The maximum rated voltage that can be applied to the EN/UVLO pin without causing permanent damage to an IC or degrading its characteristics or reliability
Output voltage	V _{OUT}	The maximum rated voltage that can be applied to the VOUT pin without causing permanent damage to an IC or degrading its characteristics or reliability
External MOSFET voltage	V _{EFET}	The maximum rated voltage that can be applied to the EFET pin without causing permanent damage to an IC or degrading its characteristics or reliability
Power dissipation	P _D	The maximum power dissipation that does not cause permanent damage to an IC over the entire operating range
Junction temperature	Tj	The maximum junction temperature tolerated by an IC
Storage temperature	T _{stg}	The ambient temperature range in which an IC can be stored and transported without voltage application

2. Operating range

Term	Symbol	Description
Input voltage	$V_{\rm IN}$	The input voltage range in which the proper operation and electrical characteristics of an IC are guaranteed
Output current	I _{OUT}	The output current range in which the proper operation and electrical characteristics of an IC are guaranteed
ILIM External resistance	R _{ILIM}	The range of the value of the resistor connected to the ILIM pin whereby the proper operation and electrical characteristics of an IC are guaranteed
Control voltage	V _{EN/UVLO}	The control voltage range in which the proper operation and electrical characteristics of an IC are guaranteed
External MOSFET voltage	V _{EFET}	The range of the EFET pin voltage in which the proper operation and electrical characteristics of an IC are guaranteed
Operating temperature	T _{a_opr}	The ambient temperature range in which the proper operation and electrical characteristics of an IC are guaranteed
External capacitor for the dV/dT pin	C _{dV/dT}	The range of the value or the maximum value of the capacitor connected to the dV/dT pin with which the proper operation and electrical characteristics of an IC are guaranteed

3. Electrical characteristics

3.1. DC characteristics

Term	Symbol	Description
Basic operation		
VIN undervoltage lockout (UVLO) rising threshold	V _{IN_UVLO}	The input voltage at which undervoltage lockout (UVLO) is disabled during a rising transition of VIN under the specified test conditions
VIN undervoltage lockout (UVLO) hysteresis	V _{IN_UVhyst}	The hysteresis width between the input voltage at which undervoltage lockout (UVLO) is tripped (V_{IN}) and the input voltage at which it is disabled (V_{IN_UVLO})
EN/UVLO threshold voltage, rising	V _{ENR}	The voltage at the EN/UVLO pin at which an IC is guaranteed to turn on under the specified test conditions
EN/UVLO threshold voltage, falling	V _{ENF}	The voltage at the EN/UVLO pin at which an IC is guaranteed to turn off under the specified test conditions
On resistance	R _{ON}	The on-resistance between the VIN and VOUT pins under the specified test conditions
Quiescent current (ON state)	IQ	The current that flows through an IC under the specified test conditions when it is on
Quiescent current (OFF state)	$I_{Q(OFF)}$	The current that flows through an IC under the specified test conditions when it is off
dV/dT control		
CdV/dT voltage	V _{dV/dT}	The voltage at the dV/dT pin under specified test conditions
Charging current	I _{dV/dT}	The current sourced from the dV/dT pin under the specified test conditions
Discharge resistance	R _{dV/dT}	The resistance between the dV/dT and GND pins under the specified test conditions
dV/dT-to-OUT gain	GAIN _{dV/dT}	The ratio of the dV/dT pin voltage to the output voltage. This is guaranteed by virtue of design and is not tested in production.

Term	Symbol	Description
External FET gate driver		
Charging current	I _{efet}	The current sourced from the EFET pin under the specified test conditions. The gate of an external N-channel MOSFET is charged by this current.
Output voltage	V _{EFET}	The voltage at the EFET pin under specified test conditions
Discharge resistance	R _{EFET}	The value of the resistor between the EFET and GND pins under the specified test conditions. The gate of an external N-channel MOSFET is discharged through this resistor.
Overvoltage lockout		
Overvoltage clamp (OVC)	Vovc	The voltage level at which the output is clamped by the overvoltage protection function under the specified test conditions
Overcurrent protection		
Overcurrent limit	I _{LIM} (I _{OUT_CL})	The current level at which the output is clamped by the overcurrent protection function under the specified test conditions
Short-circuit current limit	I _{SCL}	The output current that flows when the output pin (VOUT) is kept in the short-circuited state under the specified test conditions. This is guaranteed by virtue of design and is not tested in production.
Fast trip comparator level	I _{fasttrip} (I _{short_trip})	The output current at which short-circuit protection is tripped under the specified test conditions
ILIM short resistor detect threshold	R _{SHORTLIM}	The resistor value at which R_{ILIM} connected to the ILIM pin is determined to be short-circuited. This is guaranteed by virtue of design and is not tested in production.
Thermal shutdown (TSD)		
Thermal shutdown threshold temperature	T _{SD}	The junction temperature at which an IC is shut down by the TSD function under the specified test conditions
Thermal shutdown hysteresis	T _{SDH}	The hysteresis width between the junction temperature at which the TSD function is disabled to turn an IC back on and the thermal shutdown threshold temperature (T_{SD})

3.2. AC characteristics

Term	Symbol	Description
V _{OUT} on time	t _{ON}	The time required under the specified test conditions from when a Low-to-High transition is applied to the EN/UVLO input pin to when V_{OUT} (I_{OUT}) rises to the specified condition. This characteristic is specified only as a guide.
V _{OUT} off time	t _{OFF}	The time required under the specified test conditions from when a High-to-Low transition is applied to the EN/UVLO input pin to when V_{OUT} (I_{OUT}) falls to the specified condition. This characteristic is specified only as a guide.
Output ramp time	t _{dV/d⊤}	The time required under the specified test conditions from when a Low-to-High transition is applied to the EN/UVLO input pin to when V_{OUT} (I_{OUT}) rises to the specified condition. This characteristic is specified only as a guide.
Fast trip comparator delay	t _{FastOff} Dly	The time required under the specified test conditions from when the output pin (VOUT) is short-circuited to when the output current (I_{OUT}) turns off. This characteristic is specified only as a guide.
EFET on time	t _{EFET-ON}	The time required under the specified test conditions from when a Low-to-High transition is applied to the EN/UVLO input pin to when the EFET pin voltage (V_{EFET}) rises to the specified voltage. This characteristic is specified only as a guide.
EFET off time	t _{EFET-OFF}	The time required under the specified test conditions from when a High-to-Low transition is applied to the EN/UVLO input pin to when the EFET pin voltage (V_{EFET}) falls to the specified voltage. This characteristic is specified only as a guide.

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4. Related Links

■Product Line Ups (Catalog)	Click
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